

Express Mail No.: EV529787097US
International Application No.: PCT/JP2004/017397
International Filing Date: November 11, 2004
Preliminary Amendment

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) A conductive paste containing an acrylic system resin as a binder and at least one solvent selected from a group consisting of limonene, α -terpinyl acetate, I-dihydrocarvyl acetate, I-menthone, I-perillyl acetate, I-carvyl acetate, and d-dihydrocarvyl acetate as a solvent.
2. (Original) A conductive paste in accordance with Claim 1, wherein the weight-average molecular weight of the acrylic system resin is equal to or larger than 450,000 and equal to or smaller than 900,000.
3. (Currently Amended) A conductive paste in accordance with Claim 1 ~~or 2~~, wherein the acid value of the acrylic system resin is equal to or larger than 5 mgKOH/g and equal to or smaller than 25 mgKOH/g.
4. (Original) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component comprising a step of printing a conductive paste containing an acrylic system resin as a binder and at least one solvent selected from a group consisting of limonene, α -terpinyl acetate, I-dihydrocarvyl acetate, I-menthone, I-perillyl acetate, I-carvyl acetate, and d- dihydrocarvyl acetate as a solvent on a ceramic green sheet containing a butyral system resin as a binder in a predetermined pattern to form an electrode layer.

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5. (Original) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 4, which further comprises a step of printing a dielectric paste containing an acrylic system resin as a binder and at least one solvent selected from a group consisting of limonene, α -terpinyl acetate, I-dihydrocarvyl acetate, I-menthone, I-perillyl acetate, I-carvyl acetate, and d-dihydrocarvyl acetate as a solvent on the ceramic green sheet in a complementary pattern to that of the electrode layer after drying the electrode layer, thereby forming a spacer layer.

6. (Original) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 4, which further comprises a step of printing a dielectric paste containing an acrylic system resin as a binder and at least one solvent selected from a group consisting of limonene, α -terpinyl acetate, I-dihydrocarvyl acetate, I-menthone, I-perillyl acetate, I-carvyl acetate, and d-dihydrocarvyl acetate as a solvent on the ceramic green sheet in a complementary pattern to that of the electrode layer prior to forming the electrode layer, thereby forming a spacer layer.

7. (Currently Amended) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with ~~any one of~~ Claims 4-to-6, wherein the weight-average molecular weight of the acrylic system resin is equal to or larger than 450,000 and equal to or smaller than 900,000.

8. (Currently Amended) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with ~~any one of~~ Claims 4-to-7, wherein the acid value of the acrylic system resin is equal to or larger than 5 mgKOH/g and equal to or smaller than 25 mgKOH/g.

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9. (Currently Amended) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with ~~any one of~~ Claims 4-to-8, wherein the degree of polymerization of the butyral system resin is equal to or larger than 1,000.

10. (Currently Amended) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with ~~any one of~~ Claims 4-to-9, wherein the butyral degree of the butyral system resin is equal to or larger than 64 mol % and equal to or smaller than 78 mol %.